



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

October 10, 2003

1714 \$

Applicants : Tetsuo NISHIKAWA et al
Title : THERMOPLASTIC RESIN COMPOSITION
Serial No. : 09/973 646 Group: 1714
Confirmation No.: 6210
Filed : October 9, 2001 Examiner: Shosho
Atty. Docket No.: Nanjo Case 1
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Herewith is an amendment in the above-identified application.

[] Applicant claims small entity status. See 37 CFR 1.27.

[] The additional filing fee has been calculated as shown below:

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For	No. Filed	No. Extra	(X) LG Entity	RATE	() SM Entity	Fee
Basic Fee			\$770.00		\$385.00	\$
Total Claims	(11 - 20 = 0)		x \$ 18.00		x \$ 9.00	
Indep. Claims	(2 - 3 = 0)		x \$ 86.00		x \$ 43.00	
[] Multiple Dep. Claim			+ \$290.00		+ \$145.00	
* * * TOTAL FILING FEE * * *						\$ 0.00

- [X] Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by one month. The extension fee is: \$110.00.
- [X] A Check for \$110.00 is enclosed to cover fees.
- [X] Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382. A duplicate copy of this sheet is enclosed.

IN DUPLICATE

TFC/smd


Terryence F. Chapman Reg. No. 32 549

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on October 10, 2003.

130.10/03


Terryence F. Chapman